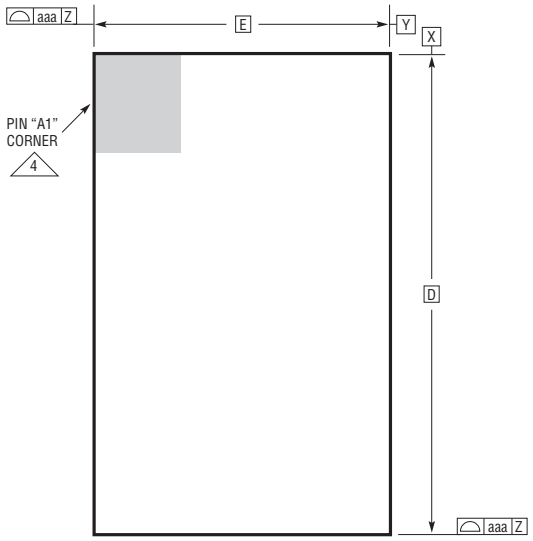
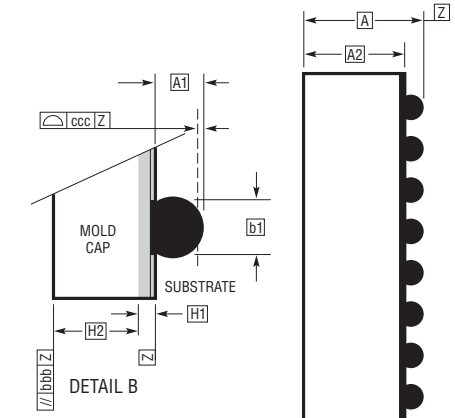
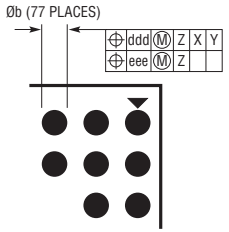
BGA Package
77-Lead (15.00mm × 9.00mm × 5.01mm)
(Reference LTC DWG# 05-08-1900 Rev D)



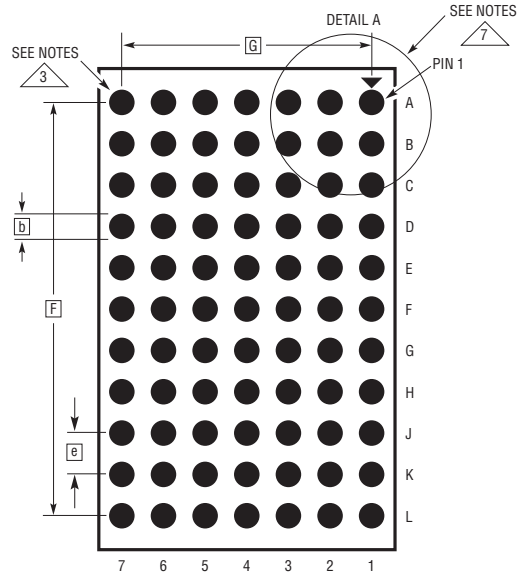
PACKAGE TOP VIEW



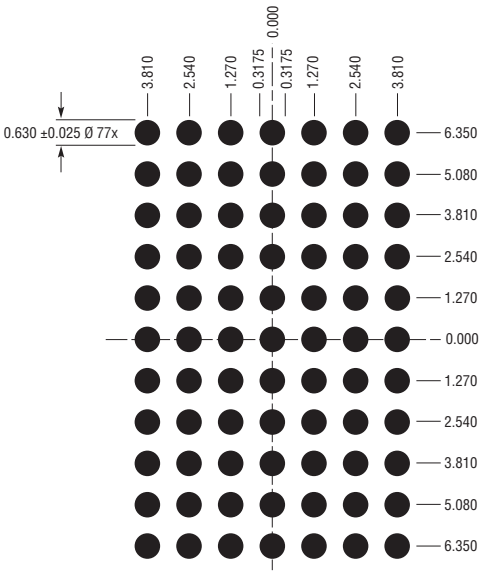


DETAIL A

DETAIL B
PACKAGE SIDE VIEW



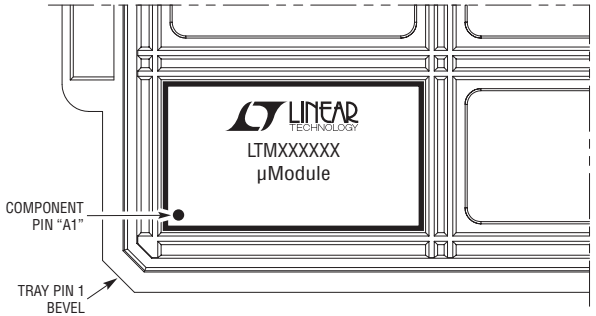
PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	4.81	5.01	5.21	
A1	0.50	0.60	0.70	
A2	4.31	4.41	4.51	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D		15.00		
E		9.00		
e		1.27		
F		12.70		
G		7.62		
H1	0.36	0.41	0.46	
H2	3.95	4.00	4.05	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 77				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 77 0113 REV D